

ABSTRACT:

Method of soldering components on a carrier foil.

The invention relates to a method of soldering components on a carrier foil whereby hot gas is conducted onto the lower side of the carrier foil. Special soldering methods are necessary especially in SMD technology, whereby components can be soldered in large numbers on a carrier foil in a non-destructive manner both for the component itself and for the carrier foil. According to the invention, the hot gas is aimed at a soldering spot through a nozzle, heating this spot until solder heated by the hot gas flow melts on the surface of the carrier foil.

Figure

10

This Sheet Has Been Replaced

